

A low viscosity, flowable epoxy

5336 is a black, electrically isolating, thermally conductive epoxy designed specifically for staking and encapsulating electronics on circuit boards as well as potting and encapsulating power supplies, transformers, and coils. This material is ideal for applications requiring a thermally conductive epoxy with resistance to solvents and chemicals. 5336 is supplied in frozen syringes.

UNCURED	
Pot Life @ 25°C	1.5 hours
Viscosity, Mixed, @ 25°C	39,500 cPs
Shelf Life	12 months @ -60°C 6 months @ -40°C 12 months @ 25°C
Mix Ratio 100A	6B Parts by Weight
CURE OPTIONS	2 hours @ 80°C 4 hours @ 60°C
CURED PROPERTIES	Based on cure of 2 hours @ 80°C
Color	Black
Shore D Hardness	93
Glass Transition Temp (°C)	63
Density (g/cc)	2.5
Lap Shear (psi)	2040
ELECTRICAL PROPERTIES	Based on cure of 2 hours @ 80°C
Dielectric Constant	5.99 @ 100 kHz
Dissipation Factor	0.14 @ 100 kHz
Dielectric Strength (volts/mil)	478
Volume Resistivity (ohm-cm)	3.5E+15 @ 500 VDC
THERMAL PROPERTIES	Based on cure of 2 hours @ 80°C
Glass Transition Temp (°C)	63
Degradation Temp. (°C)	300
Thermal Conductivity (W/mK)	1.48
OUTGASSING PROPERTIES	Based on cure of 2 hours @ 80°C
TML (%)	0.31
CVCM (%)	0.01
WVR (%)	0.04

KEY FEATURES

Electrically Isolating

High Thermal Conductivity

Low Shrinkage

Flowable

Low Outgassing

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